ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

30-SEP-2005

SUBJECT: ON Semiconductor Final Product/Process Change Notification #15025

TITLE: Assembly Transfer of PDIP Packages from OSE-P to AIT

EFFECTIVE DATE: 30-Nov-2005

AFFECTED CHANGE CATEGORY(S): Subcontractor Assembly Site

AFFECTED PRODUCT DIVISION(S): Analog Power Management

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Bob Marquis <FC88FC@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or
William Fontes <FC8HYB@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or
Mohd Ibrahim A K B Maiden <FFN3DP@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce plans to transfer assembly of 8, 14, 16, and 18 lead PDIP packaged parts from OSE-P to Advanced Interconnect Technology (AIT), located in Batam, Indonesia.
The transfer is a manufacturing consolidation measure.
AIT is QS9000, ISO9002, and TS16949 certified, and it has been a qualified assembly subcontractor for ON Semiconductor since 1990.
AIT is qualified and currently assembling other Analog products for ON Semiconductor in 8, 14, 16, 18, 20, and 24 pin PDIP packages.
In the case of Analog 14/16 lead PDIP products, AIT is the primary supplier for ON Semiconductor. The transferred devices will use AIT's standard Build of materials(BOM). Device parameters will continue to meet all Data Book specifications, and the reliability of the products will continue to meet or exceed ON Semiconductor standards.

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RELIABILITY DATA SUMMARY:

The qualification testing was successfully performed (all tests passed) on the SCY994401P device type, a 16 Lead fused-frame PDIP packaged part. This device was selected as the qualification vehicle based upon its large size. Completed Reliability Tests are as follows:

Test	Conditions	Sample Size	Duration
Op-life (HTOL)	Biased at +125C	77 Units/lot	504 Hours
Temperature Cycle (TC)	-65C to +150C	77 Units/lot	500 Cycles
Unbiased HAST (UHAST)	+130C/85% RH	77 Units/lot	96 Hours
Autoclave (AC)	+121C/100% RH/15 PSIG	77 Units/Lot	96 Hours
Wire Bond Pull Strength (BPS)	After TC Test	30 Bonds/5 units	
Solderability (SD)	Steam age at +260C	15 Units/lot	8 Hours
Solderability (SD)	Steam age at +310C	15 Units/lot	8 Hours
Physical Dimensions (PD)	Per case outline	30 Units/lot	

Note: The qualification testing entailed samples from 1 lot for the HTOL, SD, BPS, and PD evaluations and from 3 lots for the TC, UHAST, and AC tests.

There is also extensive generic reliability data already available within ON Semiconductor on the 8, 14 and 16 lead (Nonfused leadframes)PDIP packages assembled at AIT.

ELECTRICAL CHARACTERISTIC SUMMARY:

No measurable differences were observed at probe or final test. The assembly change has no impact to device electrical performance.

CHANGED PART IDENTIFICATION:

No physical changes to the package outlines. Parts assembled at AIT can be identified by the "CP" factory code on the package.

AFFECTED DEVICE LIST

PART

CS2841BEBN8
CS41014BN8
CS4121ENF16
CS44076N8
CS45092NF16
CS45134BN14
CS46054N8
CS5101EN14
CS68051NF16
CS68059NF16
CS68096NF16
CS69061N8
CS8151CGN8
CS8151YNF16
CS8190ENF16
CS92404BN16
CS93801N16
NCV7601P
SCV697601P
SCY994401P